



Line Card



Chip Supply is not limited to the manufacturers listed above.
Please contact your sales representative for all of your die and wafer needs.





Chip Supply Capabilities and Line Card

At the heart of Chip Supply's products and value added services is the silicon produced by our Semiconductor Partners. Working closely with the leading semiconductor manufacturers, Chip Supply "bridges the gap" between the industry's standard product offerings and your interconnect needs. With capabilities that include wafer processing, electrical test, software development, environmental screening, package design and assembly, and a host of other value added services, Chip Supply can provide the right interconnect approach to meet your performance and budget demands.

From providing bare die and obsolete military packaging, to a custom designed CSP or module, Chip Supply is..

"Thinking Beyond Silicon!"

Capabilities

- Wafer saw
- Visual inspection per MIL-STD or custom
- Wafer thinning
- Wafer bumping and RDL
- Electrical Test, Lot Qualification, Environmental Screening
- Known Good Die (KGD)
 - Equivalent quality and reliability to packaged device
- Hermetic Package Assembly
 - QML certified assembly line – MIL-PRF-38535
- Chip Scale Packaging (CSP)
- Few-die Modules / SIP
- Tape Automated Bond or Tape Carrier Packaging (TCP)
- Die Banking / Obsolescence Management

Sales Offices

Headquarters—Orlando, FL
407.298.7100

Northeast Office—Philadelphia, PA
Christine Unger—215.943.5103

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